# International

Preliminary Data Sheet No. PD60035J IR2152 (NOTE: For new designs, we recommend IR's new products IR2154 and IR21541)

## SELF-OSCILLATING HALF-BRIDGE DRIVER

#### Features

- Floating channel designed for bootstrap operation Fully operational to +600V
  Tolerant to negative transient voltage dV/dt immune
- Undervoltage lockout
- Programmable oscillator frequency

## $f = \frac{1}{1.4 \times (\mathsf{R}_{\mathsf{T}} + 75\Omega) \times \mathsf{C}_{\mathsf{T}}}$

- Matched propagation delay for both channels
- Low side output in phase with RT

#### Description

The IR2152 is a high voltage, high speed, selfoscillating power MOSFET and IGBT driver with both high and low side referenced output channels. Proprietary HVIC and latch immune CMOS technologies enable ruggedized monolithic construction. The front end features a programmable oscillator which is similar to the 555 timer. The output drivers feature a high pulse current buffer stage and an internal deadtime designed for minimum driver cross-conduction. Propagation delays for the two channels are matched to simplify use in 50% duty cycle applications. The floating channel can be used to drive an N-channel power MOSFET or IGBT in the high side configuration that operates off a high voltage rail up to 600 volts.

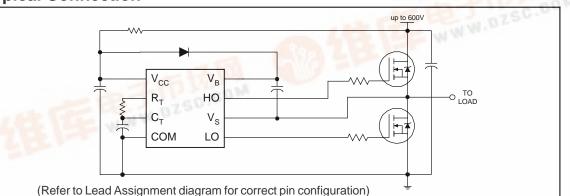
#### **Product Summary**



#### Packages



#### Typical Connection





## IR2152

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#### **Absolute Maximum Ratings**

Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM. The Thermal Resistance and Power Dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition		Min.	Max.	Units
VB	High side floating supply voltage		-0.3	625	
Vs	High side floating supply offset voltage		V <sub>B</sub> - 25	V <sub>B</sub> + 0.3	
V <sub>HO</sub>	High side floating output voltage		V <sub>S</sub> - 0.3	V <sub>B</sub> +0.3	
VLO	Low side output voltage		-0.3	V <sub>CC</sub> + 0.3	V
V <sub>RT</sub>	R <sub>T</sub> voltage		-0.3	V <sub>CC</sub> + 0.3	
VCT	C <sub>T</sub> voltage		-0.3	V <sub>CC</sub> + 0.3	
ICC	Supply current (note 1)		—	25	mA
I <sub>RT</sub>	R <sub>T</sub> output vurrent		-5	5	
dV <sub>s</sub> /dt	Allowable offset supply voltage transient		—	50	V/ns
PD	Package power dissipation @ $T_A \le +25^{\circ}C$	(8 Lead DIP)	—	1.0	w
		(8 Lead SOIC)	—	0.625	VV V
R <sub>THJA</sub>	Thermal resistance, junction to ambient	(8 Lead DIP)	—	125	°C/W
		(8 Lead SOIC)	—	200	- C/VV
TJ	Junction temperature		_	150	
Τ <sub>S</sub>	Storage temperature		-55	150	°C
TL	Lead temperature (soldering, 10 seconds)		_	300	

#### **Recommended Operating Conditions**

The input/output logic timing diagram is shown in figure 1. For proper operation the device should be used within the recommended conditions. The  $V_S$  offset rating is tested with all supplies biased at 15V differential.

Symbol	Definition	Min.	Max.	Units
VB	High Side Floating Supply Absolute Voltage	V <sub>S</sub> + 10	V <sub>S</sub> + 20	
Vs	High Side Floating Supply Offset Voltage	—	600	V
V <sub>HO</sub>	High Side Floating Output Voltage	Vs	VB	V
VLO	Low Side Output Voltage	0	V <sub>CC</sub>	
Icc	Supply Current (Note 1)	—	5	mA
TA	Ambient Temperature	-40	125	°C

Note 1: Because of the IR2152's application specificity toward off-line supply systems, this IC contains a zener clamp structure between the chip V<sub>CC</sub> and COM which has a nominal breakdown voltage of 15.6V. Therefore, the IC supply voltage is normally derived by forcing current into the supply lead (typically by means of a high value resistor connected between the chip V<sub>CC</sub> and the rectified line voltage and a local decoupling capacitor from V<sub>CC</sub> to COM) and allowing the internal zener clamp circuit to determine the nominal supply voltage. Therefore, this circuit should not be driven by a DC, low impedance power source of greater than V<sub>CLAMP</sub>.

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#### **Dynamic Electrical Characteristics**

 $V_{BIAS}$  (V<sub>CC</sub>, V<sub>BS</sub>) = 12V, C<sub>L</sub> = 1000 pF and T<sub>A</sub> = 25°C unless otherwise specified.

Symbol	Definition	Min.	Тур.	Max.	Units	<b>Test Conditions</b>
tr	Turn-on rise time	—	80	120		
t <sub>f</sub>	Turn-off fall time	—	40	70	ns	
DT	Deadtime	0.50	1.20	2.25	μs	
D	R <sub>T</sub> duty cycle	48	50	52	%	

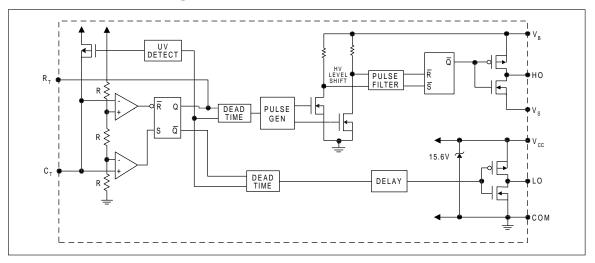
#### **Static Electrical Characteristics**

 $V_{BIAS}$  (V<sub>CC</sub>,  $V_{BS}$ ) = 12V,  $C_L$  = 1000 pF,  $C_T$  = 1 nF and  $T_A$  = 25°C unless otherwise specified. The  $V_{IN}$ ,  $V_{TH}$  and  $I_{IN}$  parameters are referenced to COM. The  $V_O$  and  $I_O$  parameters are referenced to COM and are applicable to the respective output leads: HO or LO.

Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
fosc	Oscillator frequency	19.4	20.0	20.6		R <sub>T</sub> = 35.7 kΩ
		94	100	106	kHz	R <sub>T</sub> = 7.04 kΩ
VCLAMP	V <sub>CC</sub> zener shunt clamp voltage	14.4	15.6	16.8		$I_{CC} = 5 \text{ mA}$
V <sub>CT+</sub>	2/3 V <sub>CC</sub> threshold	7.8	8.0	8.2	V	
V <sub>CT-</sub>	1/3 V <sub>CC</sub> threshold	3.8	4.0	4.2		
VCTUV	$C_T$ undervoltage lockout, $V_{CC}$ - $C_T$	—	20	50		2.5V <v<sub>CC<v<sub>CCUV+</v<sub></v<sub>
V <sub>RT+</sub>	$R_T$ high level output voltage, $V_{CC}$ - $R_T$	_	0	100		I <sub>RT</sub> = -100 μA
		—	200	300		I <sub>RT</sub> = -1 mA
V <sub>RT-</sub>	R <sub>T</sub> low level output voltage	—	20	50	mV	I <sub>RT</sub> = 100 μA
		_	200	300		I <sub>RT</sub> = 1 mA
V <sub>RTUV</sub>	R <sub>T</sub> undervoltage lockout	_	0	100		2.5V <v<sub>CC<v<sub>CCUV+</v<sub></v<sub>
VOH	High level output voltage, VBIAS - VO	_	_	100		$I_{O} = 0A$
Vol	Low level output voltage, VO	_	_	100		$I_{O} = 0A$
I <sub>LK</sub>	Offset supply leakage current	—	_	50		$V_B = V_S = 600V$
I <sub>QBS</sub>	Quiescent V <sub>BS</sub> supply current	_	10	50		
lacc	Quiescent V <sub>CC</sub> supply current	_	400	950	μA	
I <sub>CT</sub>	C <sub>T</sub> input current	—	0.001	1.0		
V <sub>CCUV+</sub>	V <sub>CC</sub> supply undervoltage positive going threshold	7.7	8.4	9.2	v	
V <sub>CCUV-</sub>	V <sub>CC</sub> supply undervoltage negative going threshold	7.4	8.1	8.9	v	
VCCUVH	V <sub>CC</sub> supply undervoltage lockout hysteresis	200	500	—	mV	
I <sub>O+</sub>	Output high short circuit pulsed current	100	125	_	mA	$V_{O} = 0V$
I <sub>0-</sub>	Output low short circuit pulsed current	210	250	_		$V_{O} = 15V$

### IR2152 Functional Block Diagram

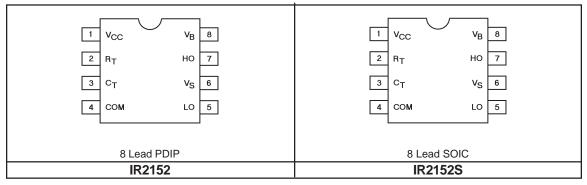
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#### **Lead Definitions**

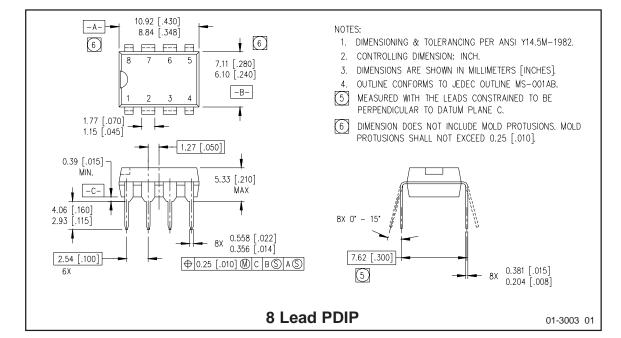
Symbol	Description		
R <sub>T</sub>	Oscillator timing resistor input, in phase with HO for normal IC operation		
CT	Oscillator timing capacitor input, the oscillator frequency according to the following equation:		
	$f = \frac{1}{1.4 \times (R_{T} + 75\Omega) \times C_{T}}$		
	where 75 $\Omega$ is the effective impedance of the R <sub>T</sub> output stage		
VB	High side floating supply		
НО	High side gate drive output		
VS	High side floating supply return		
V <sub>CC</sub>	Low side and logic fixed supply		
LO	Low side gate drive output		
COM	Low side return		

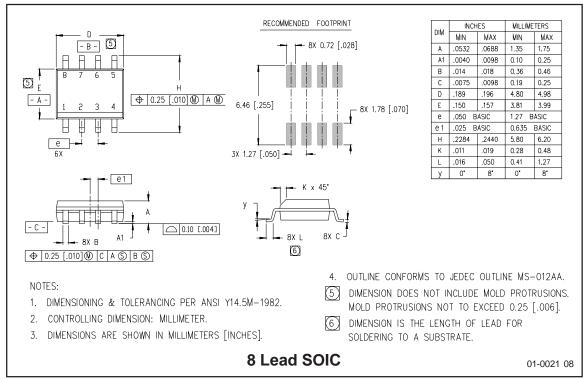
#### Lead Assignments



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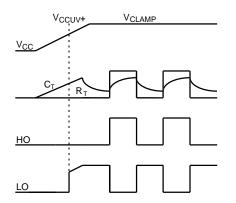
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Figure 1. Input/Output Timing Diagram

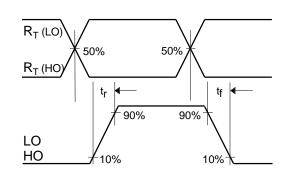


Figure 2. Switching Time Waveform Definitions

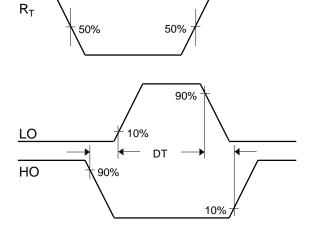


Figure 3. Deadtime Waveform Definitions



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